

ABSTRACT

A resin molding apparatus (30) includes: a mold die (C) including: an upper die (UM); and a lower die (LM); a mold clamp mechanism (35) configured to clamp the mold die (C); and a film supply mechanism (1) configured to supply a release film (F) to a space between the upper die (UM) and the lower die (LM) and including: an unwinding mechanism (11) including an unwinding roller (11a) configured to unwind the release film (F); and a film conveyor mechanism (7) configured to convey the release film (F); and a control section (6) configured to control operation of the film supply mechanism (1), the control section (6) being configured to, when the film conveyor mechanism (7) conveys the release film (F), cause the unwinding roller (11a) to rotate in a direction in which the film conveyor mechanism (7) conveys the release film (F).